



# MX555ABD100M000

## Ultra-Low Jitter 100MHz HCSL XO

### ClockWorks® FUSION

### General Description

The MX555ABD100M000 is an ultra-low phase jitter XO with HCSL output optimized for high line rate applications.

### Applications

- PCI-Express
- Storage

### Absolute Maximum Ratings

Supply Voltage (VIN).....+4.6V  
 Lead Temperature (soldering, 10s).....260°C  
 Storage Temperature (T<sub>s</sub>).....125°C  
 ESD Rating (HBM).....2kV

### Electrical Characteristics

VDD = 2.5V ±5% or 3.3V ±10%, -40°C to +85°C, outputs terminated with 50 Ohms to VSS.<sup>1</sup>

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
IDD	Supply Current				95	mA
F0	Center Frequency			100		MHz
	Frequency Stability	Note 2			±50	ppm
∅j	Phase Noise	Integration Range (12kHz to 20MHz) Integration Range (1.875MHz to 20MHz)		166 97		fsRMS
Tstart	Start-Up Time				10	ms
TR/TF	Rise/Fall time	20%-80%	150	300	450	ps
	Duty Cycle		48	50	52	%
VOH	Output High Voltage	HCSL output levels	660	700	850	mV
VOL	Output Low Voltage	HCSL output levels	-150	0	27	mV
VOVS	Max Output Including Overshoot				VOH + 0.3	V
VUDS	Min Output Including Undershoot		VOL - 0.3			V
VRB	Ringback Voltage		0.2			V
VOX	Absolute Crossing Point		250	350	550	mV
Vswing	Peak to Peak Output Voltage Swing		640	700	950	mV

#### Notes:

1. Guaranteed after thermal equilibrium.
2. Inclusive of initial accuracy, temperature drift, aging, shock, vibration.

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### Features

- 100MHz HCSL
- PCIe Gen1/Gen2/Gen3/Gen4\* compliant
- Typical phase noise:
  - 97fs (Integration range: 1.875MHz-20MHz)
- ±50ppm total frequency stability
- -40°C to +85°C temperature range
- Industry standard 6-Pin 5mm x 3.2mm LGA package

\*Internal test

### Operating Ratings

Supply Voltage (VIN).....+2.375V to +3.63V  
 Ambient Temperature (TA).....-40°C to +85°C

## Ordering Information

Ordering Part Number	Marking Line 1	Marking Line 3	Shipping	Package
MX555ABD100M000	MX555A	BD1000	Tube	6-Pin 5mm x 3.2mm LGA
MX555ABD100M000 TR	MX555A	BD1000	Tape and Reel	6-Pin 5mm x 3.2mm LGA

Devices are Green and RoHS compliant. Sample material may have only a partial top mark.

## Pin Configuration



## Pin Description

Pin Number	Pin Name	Pin Type	Pin Level	Pin Function
1	OE	I, SE	LVC MOS	Output Enable, disables output to tri-state, 0 = Disabled, 1 = Enabled, 50k Ohms Pull-Up
2	DNC			Make no connection, leave floating.
3	GND	PWR		Power Supply Ground
4, 5	Q, /Q	O, Diff	HCSL	Clock Output Frequency = 100MHz
6	VDD	PWR		Power Supply

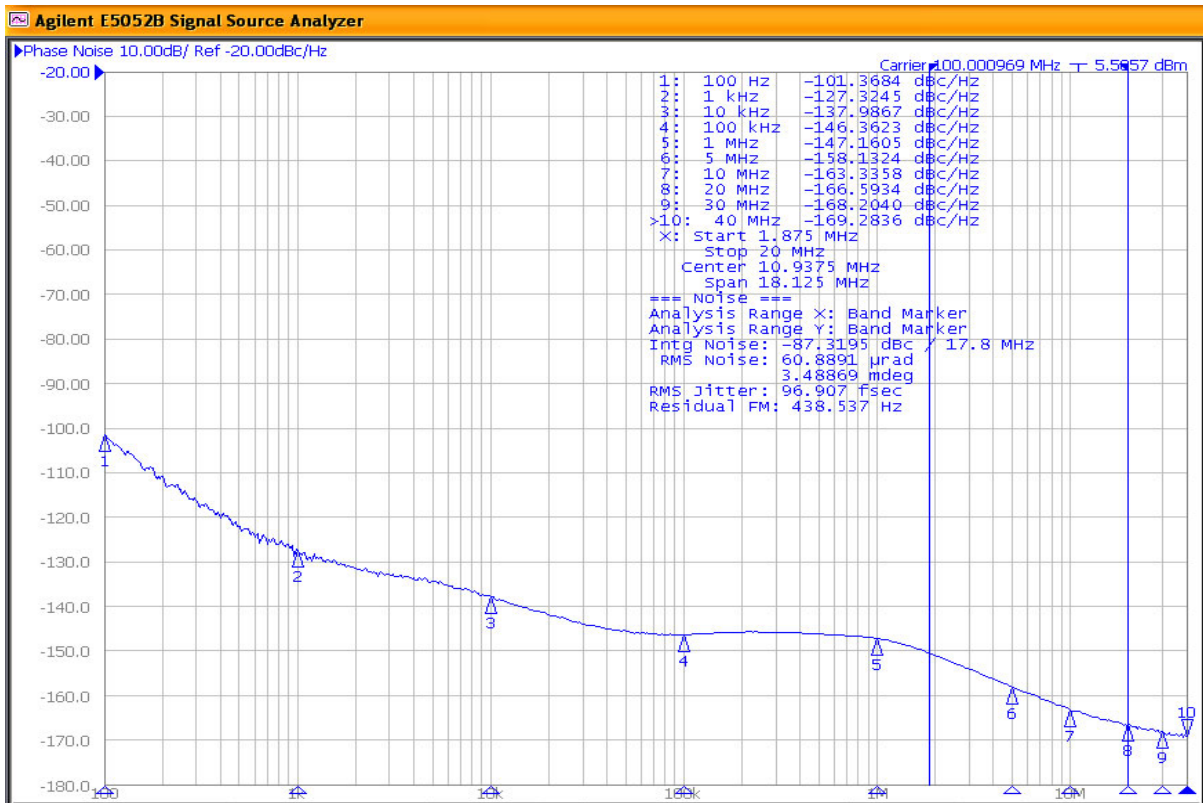


Figure 1. HCSL Output 100MHz 1.875MHz-20MHz 97fs

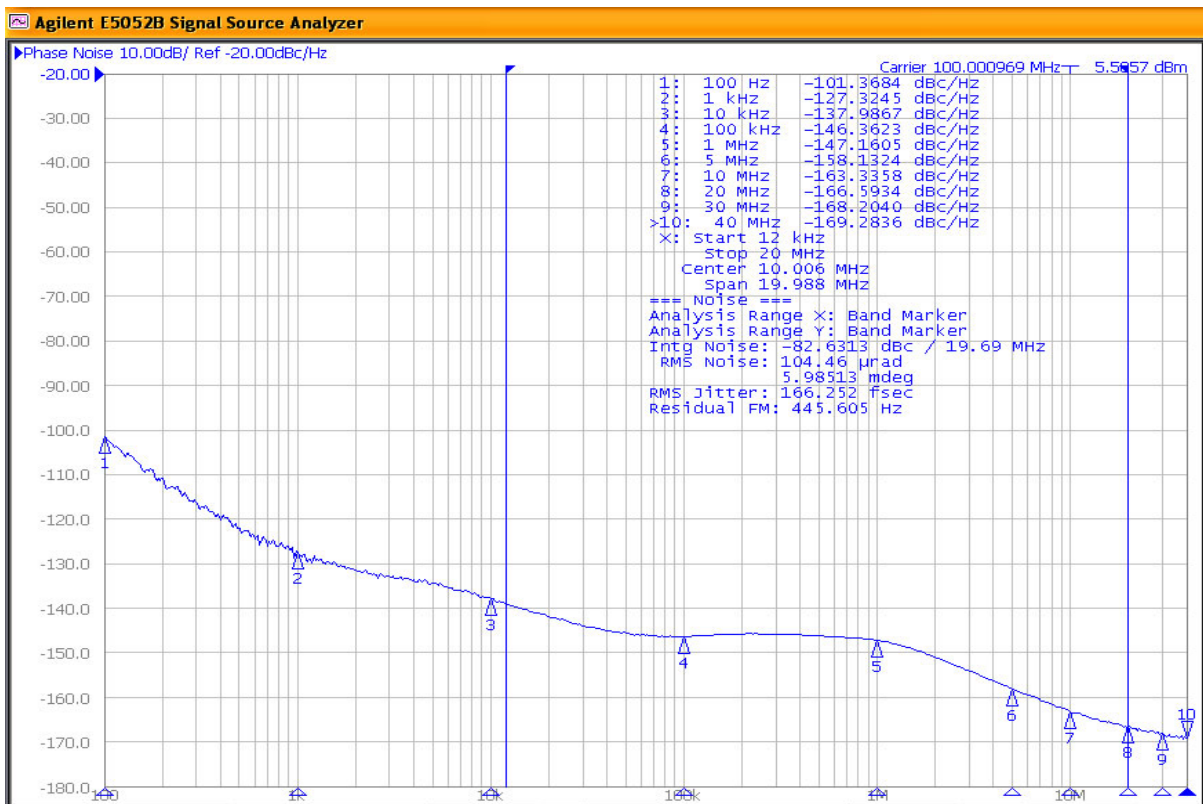
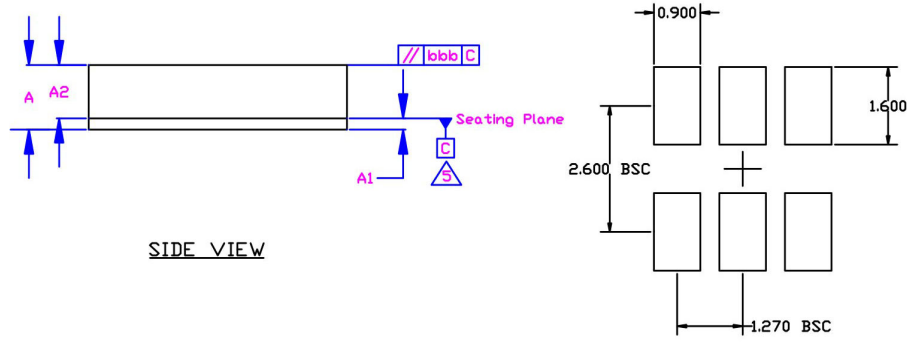
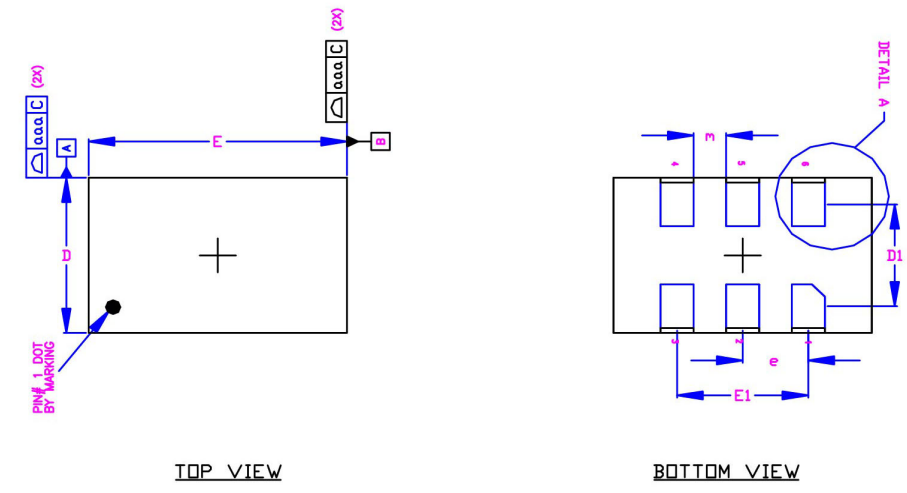


Figure 2. HCSL Output 100MHz 12kHz-20MHz 166fs

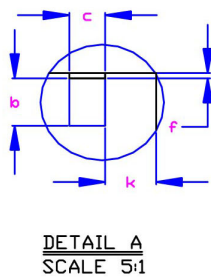
### Package Information and Recommended Land Pattern for 6-Pin LGA<sup>3</sup>



Dimensional Tol.	
aaa	0.100
bbb	0.070

Dimensional Ref.			
REF.	Min.	Nom	Max.
A	1.260	1.330	1.400
A1	0.190	0.230	0.270
A2	1.070	1.100	1.130
D	3.100	3.200	3.300
D1	2.100 BSC		
E	4.900	5.000	5.100
E1	2.540 BSC		
b	0.850	0.900	0.950
c	0.850	0.900	0.950
e	1.270 BSC		
f	0.050	0.100	0.150
k	0.860	0.910	0.960
m	0.580	0.630	0.680
n	6		



**RECOMMENDED LAND PATTERN**

- Notes**
1. Dimensioning and Tolerancing per ASME Y14.5M-1994.
  2. Dimensions are in millimeters.
  3. 'e' represents the basic LGA pitch
  4. 'n' is the maximum no. of Land for a specified Package.
  5. Package warp shall be 0.050 max.
  6. Substrate base is BT Resin
  7. The Pin#1 corner must be identified on top side only.
  8. Reference Jeduc Spec M0-220

**Note:**

3. Package information is correct as of the publication date. For updates and most current information, go to [www.microchip.com](http://www.microchip.com).

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